

ABSTRACT

The information processing apparatus (5) includes an information acquisition section (500) configured to acquire operating condition information including top-ring state information, polishing-table state information, polishing-fluid-supply-nozzle state information, dresser state information, and atomizer state information, as operating conditions under which a substrate processing apparatus performs operation of chemical mechanical polishing of a substrate. The information processing apparatus (5) further includes a state prediction section (501) configured to predict polishing-pad state information for the operating condition information by inputting the operating condition information acquired by the information acquisition section (500) to a learning model (10A) that has been generated by machine learning that causes the learning model (10A) to learn a correlation between the operating condition information and the polishing-pad state information.

FIG. 13